SMD Transformer for Ultrasonic Sensors

EP 6 series

Series/Type:	**B78416**
Ordering code:	**B78416A*A003**
Date:	2020-03-12
Version:	1

Construction

- Ferrite core
- EP 6 SMD type
- Shielding for optimized EMC-behavior
- 5 U-shape terminals

Applications

- Ultrasonic Sensor
- Ultrasonic Park Assist
- Industrial distance measuring
- Robotics

Features

- Qualification: AEC-Q200
- Resistance to reflow soldering heat in accordance to JEDEC J-STD-020D with T_{peak} 245 °C
- MSL level 1
- RoHS compatible

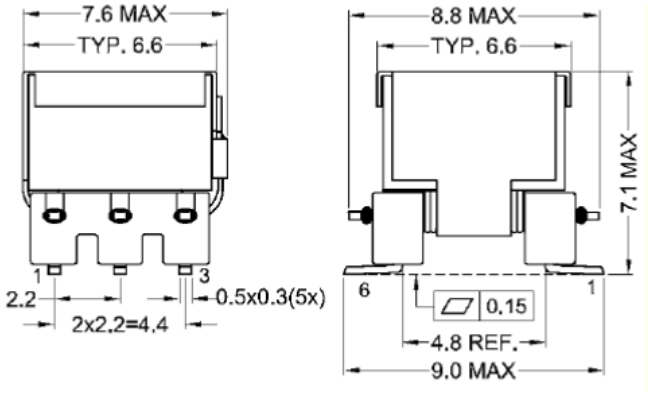
Marking

- Product brand, middle block of ordering code, date code, pin1 marker, production place identification code

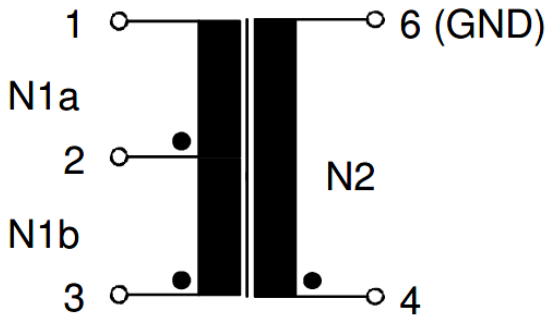
Delivery mode and packing unit

- Blister tape
- Packing unit: 1000 pcs. per reel

Dimensional drawing

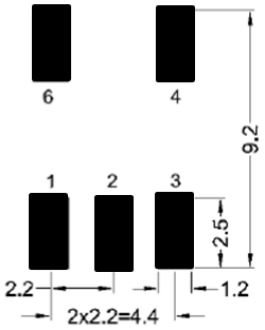


Schematics

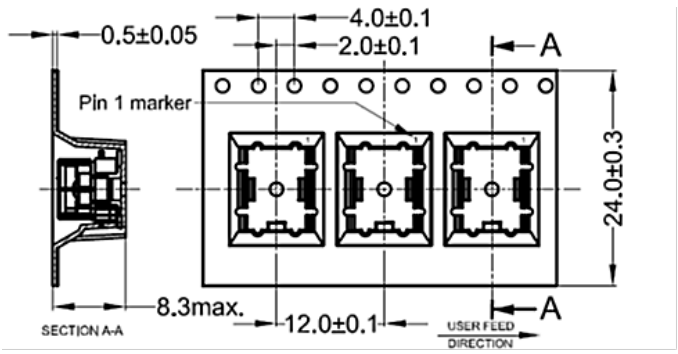


Recommendation: Connect Pin 6 on PCB to GND

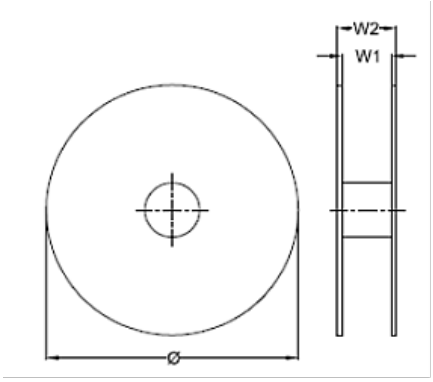
Recommended PCB layout (Top View)



Blister Tape



Reel: Ø 380 mm, W1: 24.4 mm, W2: 30.4 mm



Dimensions in [mm] / all dimensions without tolerances are typical values

Technical data and measuring conditions

Specified @ +25 °C if not mentioned otherwise / all values without tolerances are typical values

Inductance L (4 - 6)	Turns ratio $N_{1a} : N_{1b} : N_2$	R_{DC} N_{1a} / N_{1b}	R_{DC} N_2	Operating frequency	Ordering code
3 mH ±10%[1]	1 : 1 : 8.42	0.59 Ω / 0.59 Ω	23.0 Ω	52 kHz	B78416A2232A003
3 mH ±10%[1, 2]	1 : 1 : 8.42	0.59 Ω / 0.59 Ω	23.0 Ω	52 kHz	B78416A2360A003
0.23 mH ±8%[3]	1 : 1 : 9	0.23 Ω / 0.23 Ω	8.7 Ω	300 kHz	B78416A2386A003
4.2 mH ±8%[3]	1 : 1 : 15	0.55 Ω / 0.55 Ω	33 Ω	50 kHz	B78416A2430A003
5 mH ±10%[3]	1 : 1 : 10.1	0.74 Ω / 0.74 Ω	29.2 Ω	50 kHz	B78416A2433A003

High Voltage test (N1a, N1b) / N2 (f = 50 Hz, t = 1 s)	200 V_{RMS}
Weight	appr. 1 g
Operating temperature range (component)	–40 °C … +125 °C

[1] Inductance test conditions: V = 1 V, f = 52 kHz

[2] Version with short cut between shielding and Pin 6

[3] Inductance test conditions: V = 100 mV, f = 50 kHz

Cautions and warnings

- Please note the recommendations in our Inductors data book (latest edition or in the Internet) and in the data sheets.
  Particular attention should be paid to the derating curves given there. The soldering conditions should also be observed. Temperatures quoted in relation to wave soldering refer to the pin, not the housing.
- If the components are to be washed varnished it is necessary to check whether the washing varnish agent that is used has a negative effect on the wire insulation, any plastics that are used, or on glued joints. In particular, it is possible for washing varnish agent residues to have a negative effect in the long-term on wire insulation.
- The following points must be observed if the components are potted in customer applications:
  - Many potting materials shrink as they harden. They therefore exert a pressure on the plastic housing or core. This pressure can have a deleterious effect on electrical properties, and in extreme cases can damage the core or plastic housing mechanically.
  - It is necessary to check whether the potting material used attacks or destroys the wire insulation, plastics or glue.
  - The effect of the potting material can change the high-frequency behaviour of the components.
- Ferrites are sensitive to direct impact. This can cause the core material to flake, or lead to breakage of the core.
- Even for customer-specific products, conclusive validation of the component in the circuit can only be carried out by the customer.

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